COMPONENTS MARKED 'DNP' SHOULD NOT BE POPULATED.
ASSEMBLY VARIANT: .VariantName

PCB VIEWED FROM TOP SIDE

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<th>BOARD #</th>
<th>TMDXICE110</th>
<th>REV: 1.1</th>
<th>SVN REV: Not In VersionControl</th>
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PLOT NAME = Multilayer Composite Print
GENERATED : 12/26/2016 8:45:57 PM  TEXAS INSTRUMENTS
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